

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|--|------------------|---------|---------------------|
| S241 | 77 | (bond adj pad adj thickness) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/27 12:07 |
| S242 | 3 | S241 and (gap near5 height) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/27 12:08 |
| S243 | 16 | ((flip adj chip) near5 (gap near5 height)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/27 12:11 |
| S249 | 6 | (chip same board same (gap adj height) same (solder near5 (ball or interconnect or interconnect or array or grid)) same (underfill or encapsulant or encapsulat\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/27 12:18 |
| S259 | 94 | ((underfill or underfill\$3 or encapsulant or encapsulat\$3) with (before or after or prior or post or pre) with (attach\$3 or attachment or plac \$3 or align\$3) with (gap or space) with (chip or board or substrate)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/27 13:20 |

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|------|----|--|--|----|----|------------------|
| S266 | 69 | ((underfill or encapsulant or encapsulat\$3) near5 (filler near5 (particle adj size))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/04/28 10:39 |
|------|----|--|--|----|----|------------------|

4/29/2008 2:36:14 PM**C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10711501 solder interconnect array with optimal mechanical integrity 228-215 FOAM 10-03-2006.wsp**